

# Octal 3-State Noninverting Bus Transceiver

## High-Speed Silicon-Gate CMOS

### IN74AC245

The IN74AC245 is identical in pinout to the LS/ALS245, HC/HCT245. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALS outputs.

The IN74AC245 is a 3-state noninverting transceiver that is used for 2-way asynchronous communication between data buses. The device has an active-low Output Enable pin, which is used to place the I/O ports into high-impedance states. The Direction control determines whether data flows from A to B or from B to A.

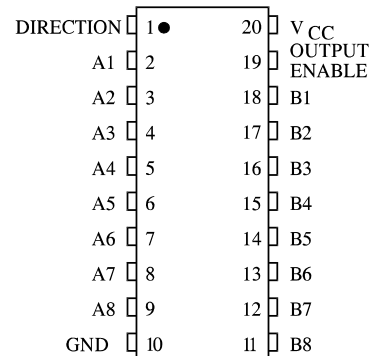
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A; 0.1  $\mu$ A @ 25°C
- High Noise Immunity Characteristic of CMOS Devices
- Outputs Source/Sink 24 mA

N SUFFIX PLASTIC

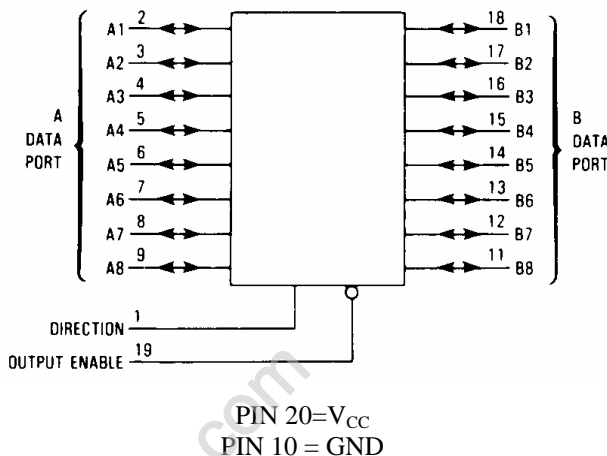
DW SUFFIX SOIC

**ORDERING INFORMATION**  
 IN74AC245N Plastic  
 IN74AC245DW SOIC  
 T<sub>A</sub> = -40° to 85° C for all packages

### PIN ASSIGNMENT



### LOGIC DIAGRAM



### FUNCTION TABLE

Control Inputs		Operation
Output Enable	Direction	
L	L	Data Transmitted from Bus B to Bus A
L	H	Data Transmitted from Bus A to Bus B
H	X	Buses Isolated (High Impedance State)

X = don't care

**MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA
I <sub>OUT</sub>	DC Output Sink/Source Current, per Pin	±50	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

\*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

SOIC Package: - 7 mW/°C from 65° to 125°C

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>J</sub>	Junction Temperature (PDIP)		140	°C
T <sub>A</sub>	Operating Temperature, All Package Types	-40	+85	°C
I <sub>OH</sub>	Output Current - High		-24	mA
I <sub>OL</sub>	Output Current - Low		24	mA
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time * (except Schmitt Inputs)	V <sub>CC</sub> =3.0 V V <sub>CC</sub> =4.5 V V <sub>CC</sub> =5.5 V	0 150 40 25	ns/V

\* V<sub>IN</sub> from 30% to 70% V<sub>CC</sub>

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>IN</sub> and V<sub>OUT</sub> should be constrained to the range GND ≤ (V<sub>IN</sub> or V<sub>OUT</sub>) ≤ V<sub>CC</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

**DC ELECTRICAL CHARACTERISTICS** (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limits		Unit
				25 °C	-40°C to 85°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V	3.0 4.5 5.5	2.1 3.15 3.85	2.1 3.15 3.85	V
V <sub>IL</sub>	Maximum Low - Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V	3.0 4.5 5.5	0.9 1.35 1.65	0.9 1.35 1.65	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	I <sub>OUT</sub> ≤ -50 μA	3.0	2.9	2.9	V
			4.5	4.4	4.4	
			5.5	5.4	5.4	
		*V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> =-12 mA		3.0	2.56	2.46
I <sub>OH</sub> =-24 mA		4.5	3.86	3.76		
I <sub>OH</sub> =-24 mA		5.5	4.86	4.76		
V <sub>OL</sub>	Maximum Low-Level Output Voltage	I <sub>OUT</sub> ≤ 50 μA	3.0	0.1	0.1	V
			4.5	0.1	0.1	
			5.5	0.1	0.1	
		*V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> =12 mA		3.0	0.36	0.44
I <sub>OL</sub> =24 mA		4.5	0.36	0.44		
I <sub>OL</sub> =24 mA		5.5	0.36	0.44		
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5	±0.1	±1.0	μA
I <sub>OZ</sub>	Maximum Three-State Leakage Current	V <sub>IN</sub> (OE)= V <sub>IH</sub> or V <sub>IL</sub> V <sub>IN</sub> =V <sub>CC</sub> or GND V <sub>OUT</sub> =V <sub>CC</sub> or GND	5.5	±0.6	±6.0	μA
I <sub>OLD</sub>	+Minimum Dynamic Output Current	V <sub>OLD</sub> =1.65 V Max	5.5		75	mA
I <sub>OHD</sub>	+Minimum Dynamic Output Current	V <sub>OHD</sub> =3.85 V Min	5.5		-75	mA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5	8.0	80	μA

\* All outputs loaded; thresholds on input associated with output under test.

+Maximum test duration 2.0 ms, one output loaded at a time.

Note: I<sub>IN</sub> and I<sub>CC</sub> @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V<sub>CC</sub>

**AC ELECTRICAL CHARACTERISTICS** ( $C_L=50\text{pF}$ , Input  $t_r=t_f=3.0\text{ ns}$ )

Symbol	Parameter	$V_{CC}^*$ V	Guaranteed Limits				Unit
			25 °C		-40°C to 85°C		
			Min	Max	Min	Max	
$t_{PLH}$	Propagation Delay, A to B, B to A (Figure 1)	3.3 5.0	1.5 1.5	8.5 6.5	1.0 1.0	9.0 7.0	ns
$t_{PHL}$	Propagation Delay, A to B, B to A (Figure 1)	3.3 5.0	1.5 1.5	8.5 6.0	1.0 1.0	9.0 7.0	ns
$t_{PZH}$	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	3.3 5.0	1.5 1.5	11.5 8.5	2.0 1.0	12.5 9.0	ns
$t_{PZL}$	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	3.3 5.0	2.5 1.5	12.0 9.0	2.0 1.0	13.5 9.5	ns
$t_{PHZ}$	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	3.3 5.0	2.0 1.5	12.0 9.0	1.0 1.0	12.5 10.0	ns
$t_{PLZ}$	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	3.3 5.0	2.0 1.5	11.5 9.0	1.5 1.0	13.0 10.0	ns
$C_{IN}$	Maximum Input Capacitance	5.0	4.5		4.5		pF
$C_{OUT}$	Maximum Three-State I/O Capacitance (I/O in High-Impedance State)	5.0	15		15		pF
$C_{PD}$	Power Dissipation Capacitance	Typical @25°C, $V_{CC}=5.0\text{ V}$				45	pF

\*Voltage Range 3.3 V is 3.3 V  $\pm$ 0.3 V  
 Voltage Range 5.0 V is 5.0 V  $\pm$ 0.5 V

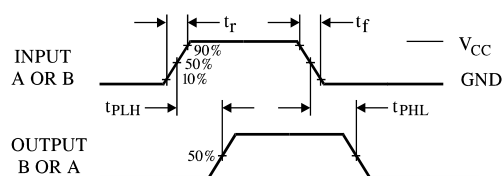


Figure 1. Switching Waveforms

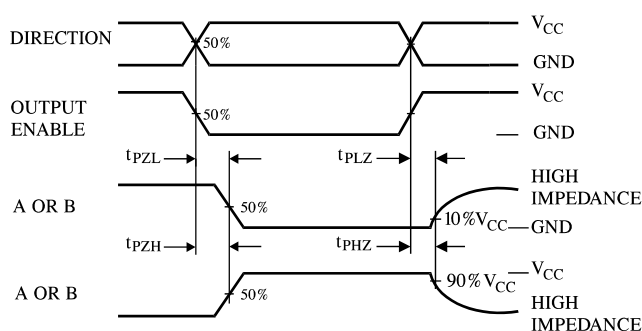
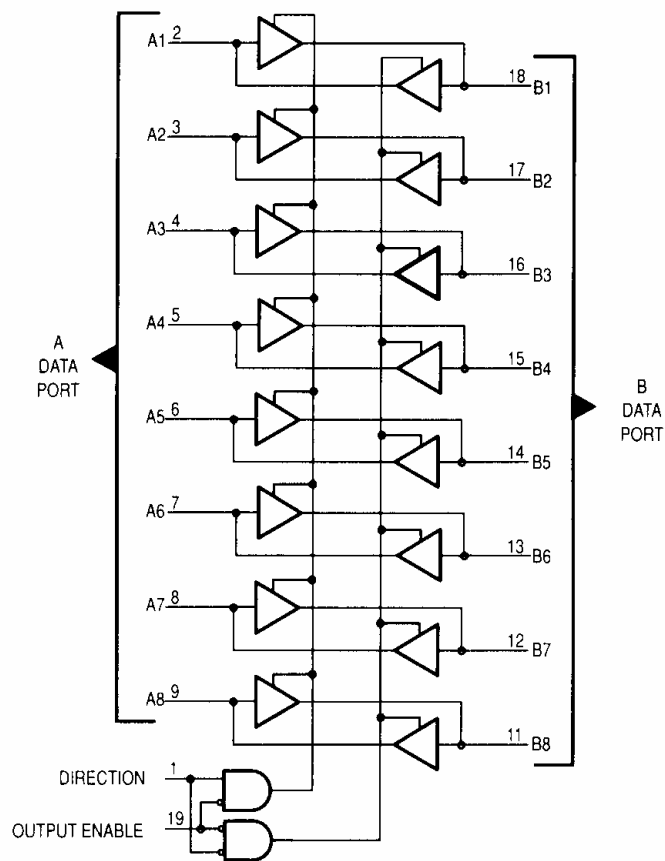
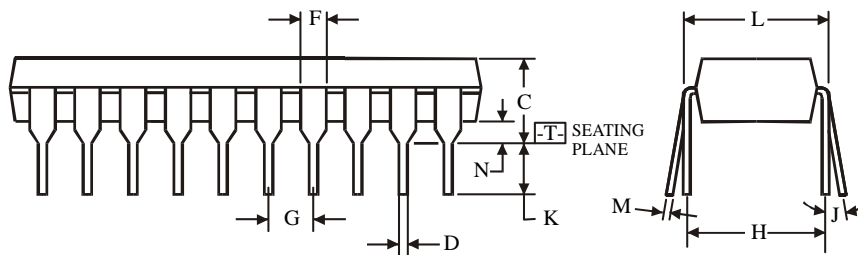
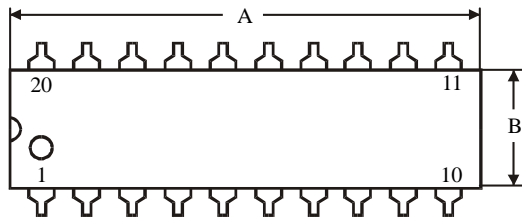
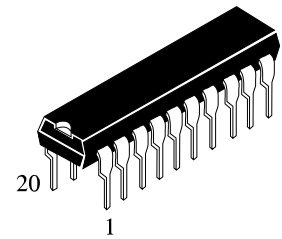


Figure 2. Switching Waveforms

EXPANDED LOGIC DIAGRAM



**N SUFFIX PLASTIC DIP  
(MS - 001AD)**



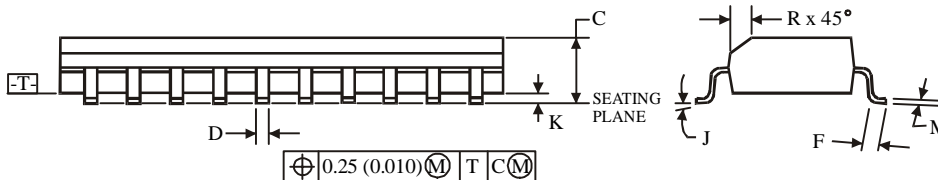
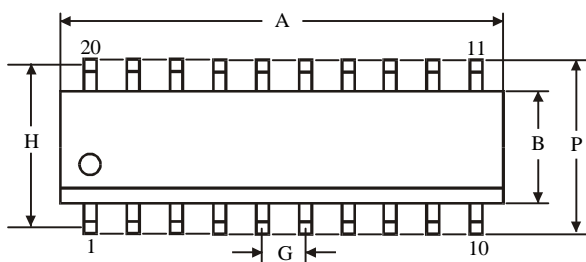
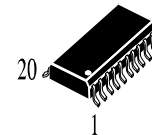
$\oplus 0.25 (0.010) \text{M} \text{T}$

**NOTES:**

- Dimensions "A", "B" do not include mold flash or protrusions.  
Maximum mold flash or protrusions 0.25 mm (0.010) per side.

Symbol	Dimension, mm	
	MIN	MAX
A	24.89	26.92
B	6.1	7.11
C		5.33
D	0.36	0.56
F	1.14	1.78
G	2.54	
H	7.62	
J	0°	10°
K	2.92	3.81
L	7.62	8.26
M	0.2	0.36
N	0.38	

**D SUFFIX SOIC  
(MS - 013AC)**



$\oplus 0.25 (0.010) \text{M} \text{T} \text{CM}$

**NOTES:**

- Dimensions A and B do not include mold flash or protrusion.
- Maximum mold flash or protrusion 0.15 mm (0.006) per side for A; for B - 0.25 mm (0.010) per side.

Symbol	Dimension, mm	
	MIN	MAX
A	12.6	13
B	7.4	7.6
C	2.35	2.65
D	0.33	0.51
F	0.4	1.27
G	1.27	
H	9.53	
J	0°	8°
K	0.1	0.3
M	0.23	0.32
P	10	10.65
R	0.25	0.75